14-Bit Binary Counter and Oscillator

The MC14060B is a 14-stage binary ripple counter with an on-chip oscillator buffer. The oscillator configuration allows design of either RC or crystal oscillator circuits. Also included on the chip is a reset function which places all outputs into the zero state and disables the oscillator. A negative transition on Clock will advance the counter to the next state. Schmitt trigger action on the input line permits very slow input rise and fall times. Applications include time delay circuits, counter controls, and frequency dividing circuits.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

Features

- Fully Static Operation
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 V to 18 V
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Buffered Outputs Available from Stages 4 Through 10 and 12 Through 14
- Common Reset Line
- Pin-for-Pin Replacement for CD4060B
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} +0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8 Second Soldering)	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

 Temperature Derating: Plastic "P and D/DW" Packages: -7.0 mW/°C from 65°C To 125°C.



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MARKING DIAGRAMS



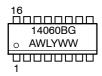
PDIP-16 P SUFFIX CASE 648 16<u>14060BCP</u>

O AWLYYWWG

1 UUUUUU



SOIC-16 D SUFFIX CASE 751B



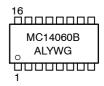


TSSOP-16 DT SUFFIX CASE 948F





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Q12 [1 ●	16] V _{DD}
Q13 [2	15] Q10
Q14 [3	14] Q8
Q6 [4	13] Q9
Q5 [5	12	RESET
Q7 [6	11	СГОСК
Q4 [7	10] OUT 1
V _{SS} [8	9	OUT 2

Figure 1. Pin Assignment

Table 1. Truth Table

Clock	Reset	Output State
١,	L	No Change
	L	Advance to Next State All Outputs are Low
н	11	All Outputs are Low

X = Don't Care

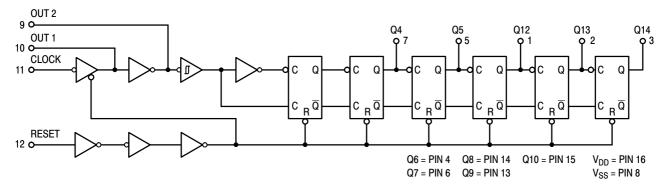


Figure 2. Logic Diagram

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14060BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14060BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14060BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14060BDTR2G	TSSOP-16*	2500 / Tape & Reel
MC14060BFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. *This package is inherently Pb-Free.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			- 5	5°C			12	5°C		
Symbol	Characteristic	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
V _{OL}	Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	V
V _{OH}	V _{in} = 0 or V _{DD} "1" Level	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	V
V _{IL}	Input Voltage "0" Level (V _O = 4.5 or 0.5 V) (V _O = 9.0 or 1.0 V) (V _O = 13.5 or 1.5 V)	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	V
V _{IH}	$(V_O = 0.5 \text{ or } 4.5 \text{ V})$ "1" Level $(V_O = 1.0 \text{ or } 9.0 \text{ V})$ $(V_O = 1.5 \text{ or } 13.5 \text{ V})$	5.0 10 15	3.5 7.0 11.0	- - -	3.5 7.0 11.0	2.75 5.50 8.25	- - -	3.5 7.0 11.0	- - -	V
V _{IL}	Input Voltage "0" Level $(V_O = 4.5 \text{ Vdc})$ (For Input 11 $(V_O = 9.0 \text{ Vdc})$ and Output 10) $(V_O = 13.5 \text{ Vdc})$	5.0 10 15	- - -	1.0 2.0 2.5	- - -	2.25 4.50 6.75	1.0 2.0 2.5	_ _ _	1.0 2.0 2.5	Vdc
V _{IH}	$(V_O = 0.5 \text{ Vdc})$ "1" Level $(V_O = 1.0 \text{ Vdc})$ $(V_O = 1.5 \text{ Vdc})$	5.0 10 15	4.0 8.0 12.5	- - -	4.0 8.0 12.5	2.75 5.50 8.25	- - -	4.0 8.0 12.5	- - -	Vdc
I _{OH}	Output Drive Current (V _{OH} = 2.5 V) (Except Source (V _{OH} = 4.6 V) Pins 9 and 10) (V _{OH} = 9.5 V) (V _{OH} = 13.5 V)	5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	- - - -	-2.4 -0.51 -1.3 -3.4	-4.2 -0.88 -2.25 -8.8	- - - -	- 1.7 - 0.36 - 0.9 - 2.4	- - - -	mA
I _{OL}	$(V_{OL} = 0.4 \text{ V})$ Sink $(V_{OL} = 0.5 \text{ V})$ $(V_{OL} = 1.5 \text{ V})$	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mA
I _{in}	Input Current	15	-	± 0.1	-	±0.00001	± 0.1	_	± 1.0	μΑ
C _{in}	Input Capacitance (V _{in} = 0)	-	-	_	-	5.0	7.5	_	-	pF
I _{DD}	Quiescent Current (Per Package)	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μΑ
I _T	Total Supply Current (Notes 3, 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	5.0 10 15			$I_T = (0$.25 μA/kHz) .54 μA/kHz) .85 μA/kHz)	f + I _{DD}			μΑ

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF: I_T(C_L) = I_T(50 pF) + (C_L – 50) Vfk where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.002.

SWITCHING CHARACTERISTICS (C_L = 50 pF, T_A = 25°C)

Symbol	Characteristic	V _{DD} Vdc	Min	Typ (Note 5)	Max	Unit
t _{TLH}	Output Rise Time (Counter Outputs)	5.0 10 15	- - -	40 25 20	200 100 80	ns
t _{THL}	Output Fall Time (Counter Outputs)	5.0 10 15	- - -	50 30 20	200 100 80	ns
t _{PLH} t _{PHL}	Propagation Delay Time Clock to Q4	5.0 10 15	- - -	415 175 125	740 300 200	ns
	Clock to Q14	5.0 10 15	- - -	1.5 0.7 0.4	2.7 1.3 1.0	μs
t _{wH}	Clock Pulse Width	5.0 10 15	100 40 30	65 30 20	- - -	ns
f_{Φ}	Clock Pulse Frequency	5.0 10 15	- - -	5 14 17	3.5 8 12	MHz
t _{TLH} t _{THL}	Clock Rise and Fall Time	5.0 10 15		No Limit		ns
t _w	Reset Pulse Width	5.0 10 15	120 60 40	40 15 10	- - -	ns
t _{PHL}	Propagation Delay Time Reset to On	5.0 10 15	- - -	170 80 60	350 160 100	ns

^{5.} Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

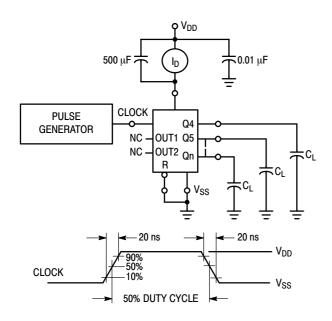


Figure 1. Power Dissipation Test Circuit and Waveform

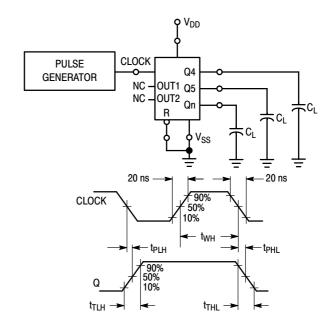
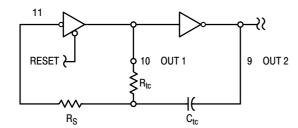


Figure 2. Switching Time Test Circuit and Waveforms



$$f \approx \frac{I}{2.3 \, R_{tc} C_{tc}}$$
 if 1 kHz \le f \le 100 kHz

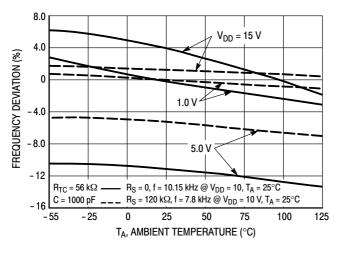
and 2R_{tc} < R_S < 10R_{tc} (f in Hz, R in ohms, C in farads)

The formula may vary for other frequencies. Recommended maximum value for the resistors in 1 $M\Omega.$

Figure 3. Oscillator Circuit Using RC Configuration

TYPICAL RC OSCILLATOR CHARACTERISTICS

100



 $V_{DD} = 10 V$ 50 f, OSCILLATOR FREQUENCY (KHz) f AS A FUNCTION 20 OF R_{TC} 10 (C = 1000 pF) $(R_S \approx 2R_{TC})$ 5 AS A FUNCTION 2 OF C $(R_{TC} = 56 \text{ k}\Omega)$ $(R_S = 120 \text{ k})$ 0.5 0.2 1.0 k 100 k 10 k 1.0 M R_{TC}, RESISTANCE (OHMS) 0.0001 0.001 0.01 0.1 C, CAPACITANCE (µF)

Figure 4. RC Oscillator Stability

Figure 5. RC Oscillator Frequency as a Function of R_{TC} and C

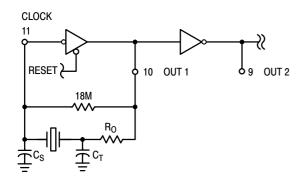


Figure 6. Typical Crystal Oscillator Circuit

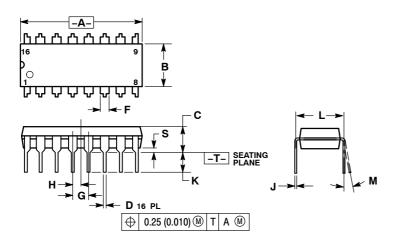
Table 2. Typical Data for Crystal Oscillator Circuit

Characteristic	500 kHz Circuit	32 kHz Circuit	Unit
Crystal Characteristics Resonant Frequency Equivalent Resistance, R _S	500 1.0	32 6.2	kHz kΩ
External Resistor/Capacitor Values RO CT CS	47 82 20	750 82 20	kΩ pF pF
Frequency Stability Frequency Changes as a Function of V _{DD} (T _A = 25°C) V _{DD} Change from 5.0 V to 10 V V _{DD} Change from 10 V to 15 V Frequency Change as a Function of Temperature (V _{DD} = 10 V) T _A Change from - 55°C to + 25°C Complete Oscillator (Note 6)	+6.0 +2.0 +100	+2.0 +2.0 +120	ppm ppm
T _A Change from + 25°C to +125°C Complete Oscillator (Note 6)	-160	–560	ppm

6. Complete oscillator includes crystal, capacitors, and resistors.

PACKAGE DIMENSIONS

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE T

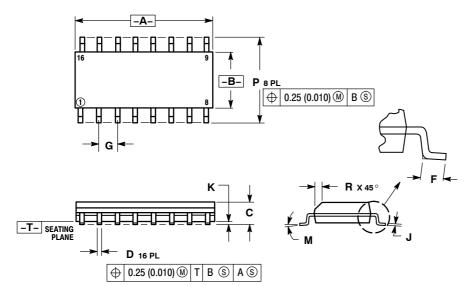


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54 BSC	
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0°	10 °	0°	10 °
S	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

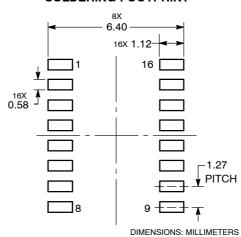
SOIC-16 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE K



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTECTION OF THE PROTECTION OF THE PROTECTION OF THE PROTECTION OF THE PROT
- PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- MAXIMUM MUCLI PROTHOLOGION 0.19 (LOUGH) FER SIDE DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

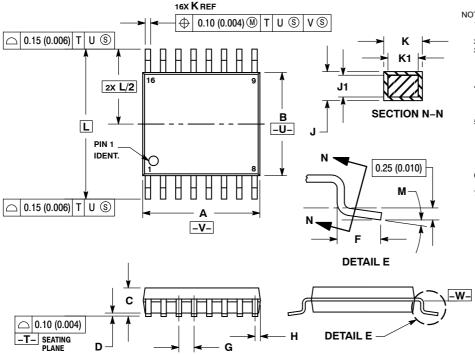
SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948F-01 **ISSUE B**



NOTES:

- JIES:

 1. DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD
 FLASH. PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 15 (2008) DED SIDE.
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

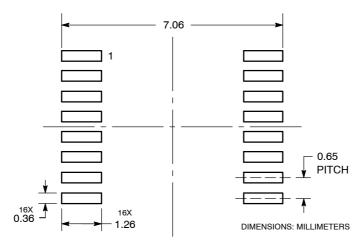
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE —W—.

MILLIMETERS INCHES						
A 4.90 5.10 0.193 0.200 B 4.30 4.50 0.169 0.177 C 1.20 0.047 D 0.05 0.15 0.002 0.006 F 0.50 0.75 0.020 0.030 G 0.65 BSC 0.026 BSC H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.008 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010		MILLIN	IETERS	INC	HES	
B 4.30 4.50 0.169 0.177 C 1.20 0.047 D 0.05 0.15 0.002 0.006 F 0.50 0.75 0.020 0.030 G 0.65 BSC 0.026 BSC H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.006 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	DIM	MIN	MAX	MIN	MAX	
C 1.20 0.047 D 0.05 0.15 0.002 0.006 F 0.50 0.75 0.020 0.030 G 0.65 BSC 0.026 BSC H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.008 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	Α	4.90	5.10	0.193	0.200	
D 0.05 0.15 0.002 0.06 F 0.50 0.75 0.020 0.030 G 0.65 BSC 0.026 BSC H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.008 K 0.19 0.30 0.007 0.010 K1 0.19 0.25 0.007 0.010	В	4.30	4.50	0.169	0.177	
F 0.50 0.75 0.020 0.030 G 0.65 BSC 0.026 BSC H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J 0.09 0.16 0.004 0.006 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	С		1.20		0.047	
G 0.65 BSC 0.026 BSC H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.006 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	D	0.05	0.15	0.002	0.006	
H 0.18 0.28 0.007 0.011 J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.006 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	F	0.50	0.75	0.020	0.030	
J 0.09 0.20 0.004 0.008 J1 0.09 0.16 0.004 0.006 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	G	0.65	0.65 BSC		BSC	
J1 0.09 0.16 0.004 0.006 K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	Н	0.18	0.28	0.007	0.011	
K 0.19 0.30 0.007 0.012 K1 0.19 0.25 0.007 0.010	J	0.09	0.20	0.004	0.008	
K1 0.19 0.25 0.007 0.010	J1	0.09	0.16	0.004	0.006	
	Κ	0.19	0.30	0.007	0.012	
L 6.40 BSC 0.252 BSC	K1	0.19	0.25	0.007	0.010	
	L	6.40 BSC		0.252	BSC	
M 0° 8° 0° 8°	M	0°	8 °	0°	8 °	

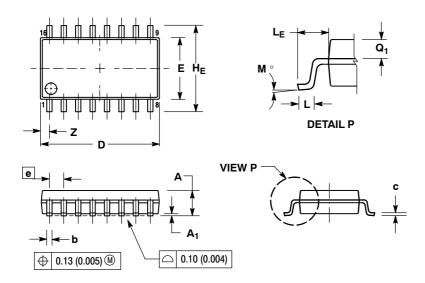
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PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE A**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Ε	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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